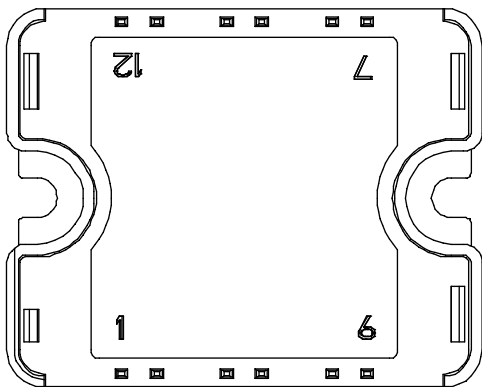
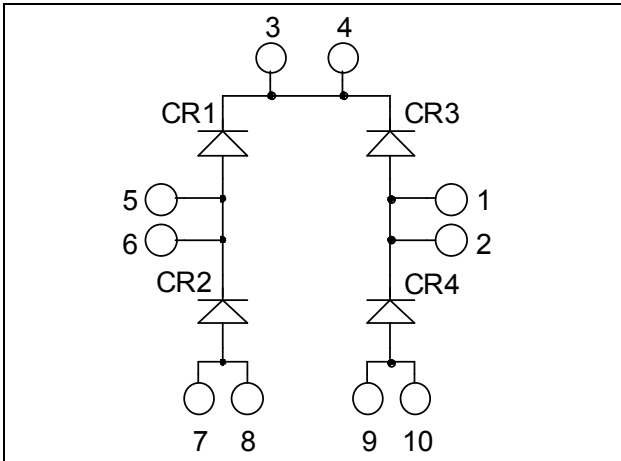


SiC Diode Full Bridge Power Module

$V_{RRM} = 600V$
 $I_F = 10A @ T_c = 80^{\circ}C$



All multiple inputs and outputs must be shorted together
 3/4 ; 5/6 ; 7/8 ; 1/2 ; 9/10

Application

- Uninterruptible Power Supply (UPS)
- Induction heating
- Welding equipment
- High speed rectifiers

Features

- **SiC Schottky Diode**
 - Zero reverse recovery
 - Zero forward recovery
 - Temperature Independent switching behavior
 - Positive temperature coefficient on VF
- Very low stray inductance
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Low losses
- Low noise switching
- Solderable terminals for easy PCB mounting
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- RoHS Compliant

Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
V_R	Maximum DC reverse Voltage	600	V
V_{RRM}	Maximum Peak Repetitive Reverse Voltage		
$I_{F(AV)}$	Maximum Average Forward Current	10	A
I_{FSM}	Non-Repetitive Forward Surge Current		
		10 μs	$T_C = 25^{\circ}C$

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

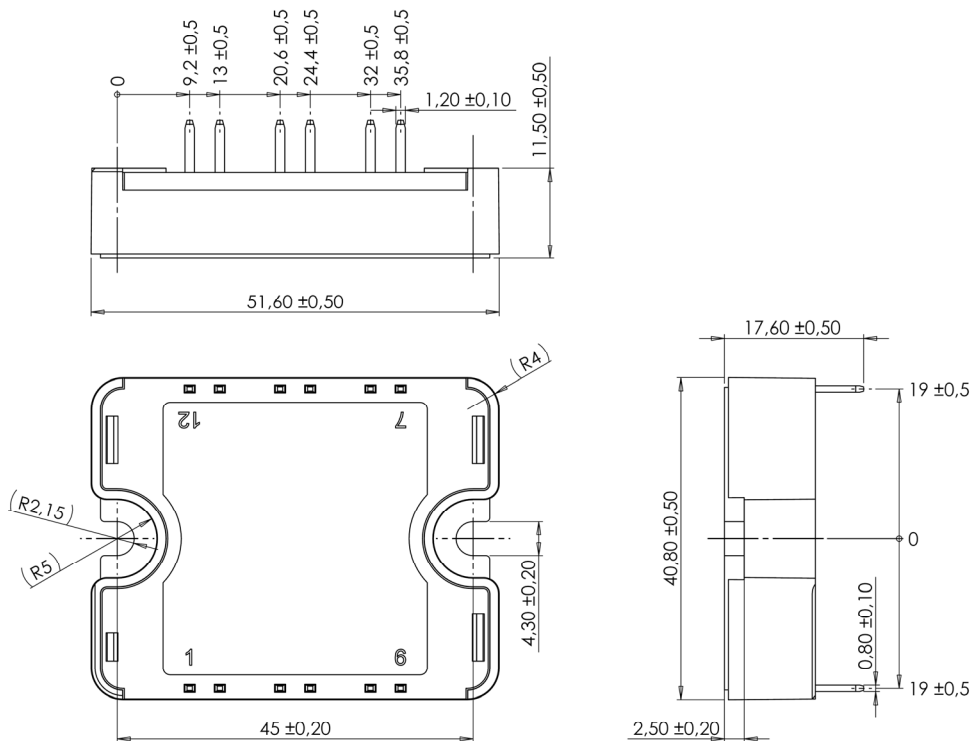
Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
V_F	Diode Forward Voltage	$I_F = 10\text{A}$	$T_j = 25^\circ\text{C}$		1.6	1.8	V
			$T_j = 175^\circ\text{C}$		2	2.4	
I_{RM}	Maximum Reverse Leakage Current	$V_R = 600\text{V}$	$T_j = 25^\circ\text{C}$		50	200	μA
			$T_j = 175^\circ\text{C}$		100	1000	
Q_C	Total Capacitive Charge	$I_F = 10\text{A}, V_R = 300\text{V}$ $di/dt = 500\text{A}/\mu\text{s}$		14		nC	
C	Total Capacitance	$f = 1\text{MHz}, V_R = 200\text{V}$		65		pF	
		$f = 1\text{MHz}, V_R = 400\text{V}$		50			

Thermal and package characteristics

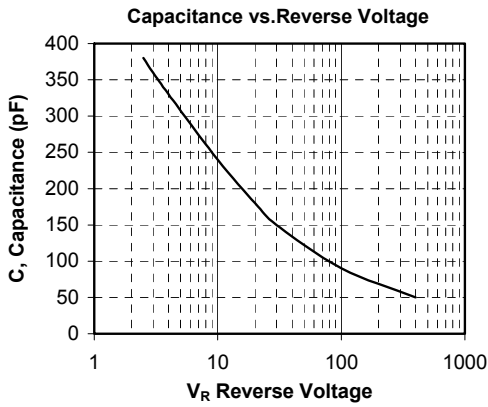
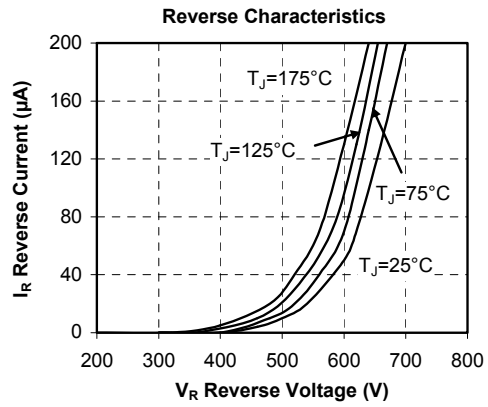
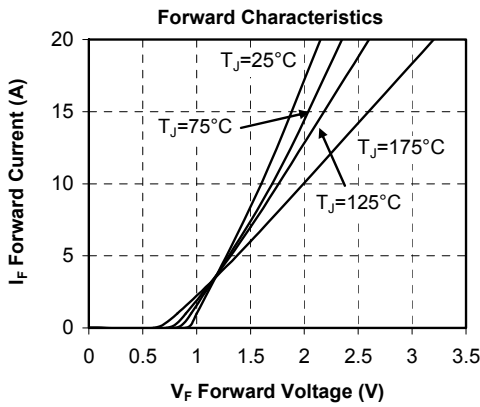
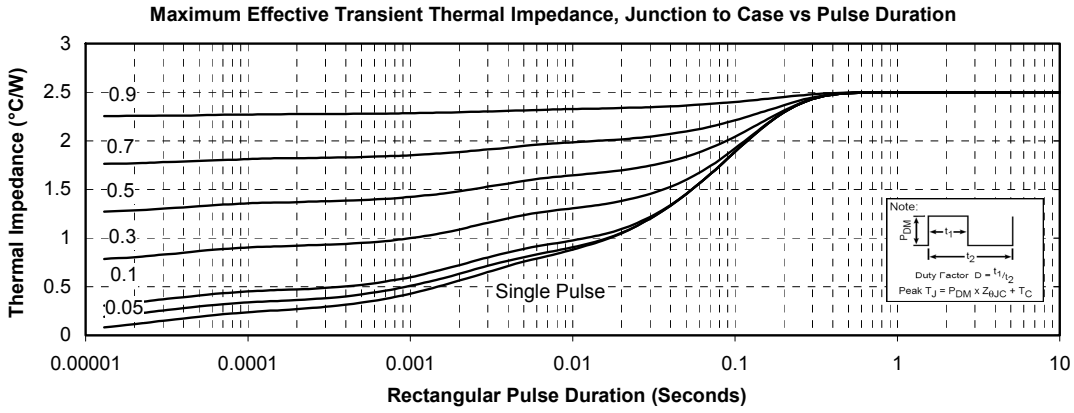
Symbol	Characteristic	Min	Typ	Max	Unit	
R_{thJC}	Junction to Case Thermal Resistance			2.5	$^\circ\text{C}/\text{W}$	
V_{ISOL}	RMS Isolation Voltage, any terminal to case $t = 1\text{ min}, 50/60\text{Hz}$	4000			V	
T_J	Operating junction temperature range	-40		175	$^\circ\text{C}$	
T_{STG}	Storage Temperature Range	-40		125		
T_C	Operating Case Temperature	-40		100		
Torque	Mounting torque	To heatsink	M4	2	3	N.m
Wt	Package Weight				80	g

SP1 Package outline (dimensions in mm)



See application note 1904 - Mounting Instructions for SP1 Power Modules on www.microsemi.com

Typical Performance Curve



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